

注記(NOTES)

- 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
- パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
- MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
- 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

DESIGN UNITS METRIC THIRD ANGLE PROJECTION

0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

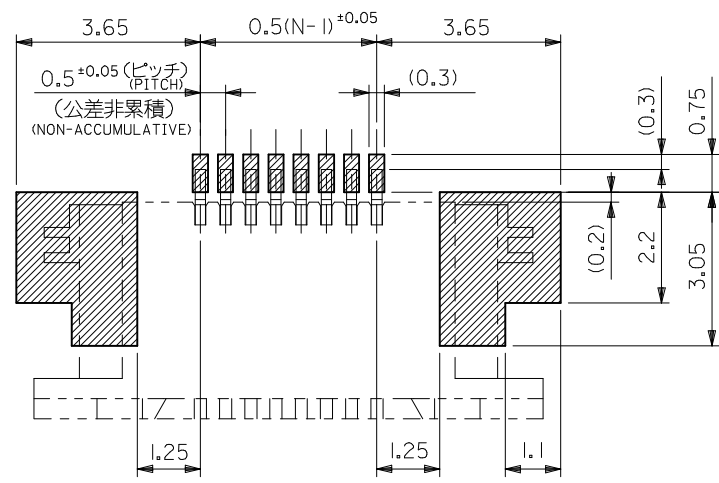
molex

DOCUMENT NO. SD-52689-034 SHEET NO. 1 OF 2

SEE SHEET 2

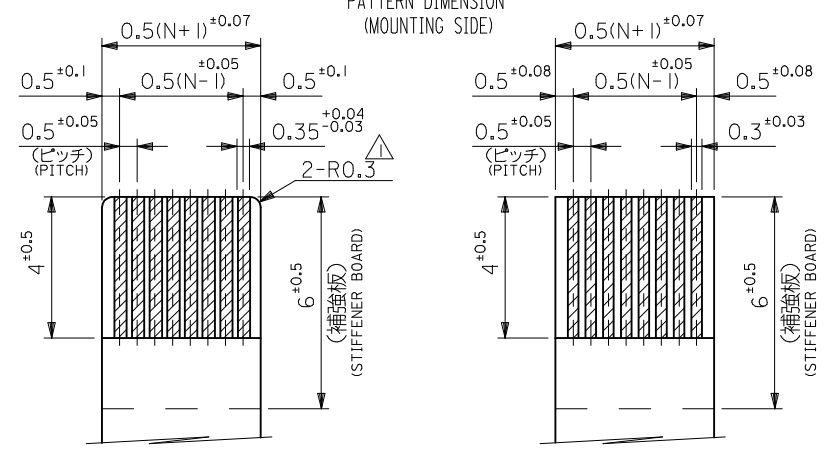
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS
0.25 UNDER	UNDER	± 0.03	MM ONLY		---	METRIC
0.25 OVER	0.5 UNDER	± 0.05	DRAWN BY	DATE	TITLE	
0.5 OVER	1.0 UNDER	± 0.1	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF	
1.0 OVER	10 UNDER	± 0.2	CHECKED BY	DATE	HSG ASSY FOR SMT(R/A)	
10 OVER	30 UNDER	± 0.25	K. TOJO	'04/02/03	-LEAD FREE-	
30 OVER		± 0.3	APPROVED BY	DATE	molex	
ANGULAR	± 3 °		M. SASAO	'04/02/03	DOCUMENT NO. SD-52689-034	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SHEET NO. 1 OF 2	
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



参考基板レイアウト (マウント面)

REFERENCE P.C. BOARD PATTERN DIMENSION (MOUNTING SIDE)



適合FPC推奨寸法 APPLICABLE FPC RECOMMENDED DIMENSION (仕上がり厚さ: 0.3±0.03) (THICKNESS: 0.3±0.03)

適合FPC推奨寸法 APPLICABLE FPC RECOMMENDED DIMENSION (仕上がり厚さ: 0.3±0.03) (THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

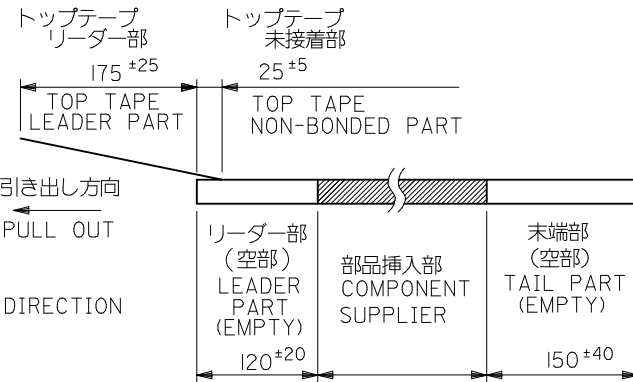
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE	極数
MODEL NO.						ORDER No. オーダー番号	CKT.

REVISED EC NO: J2016-0905 DRWN: YMIJUN002 2016/02/29 CHKD: TAKAHASHI 2016/02/29 APPR: IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		---	METRIC	
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE	
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex	
1.0 OVER	10 UNDER	±0.2	K. TOJO	'04/02/03	DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SD-52689-034	2 OF 2	
30 OVER		±0.3	M. SASAO	'04/02/03	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR	±3 °		MATERIAL NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE				
			A3				

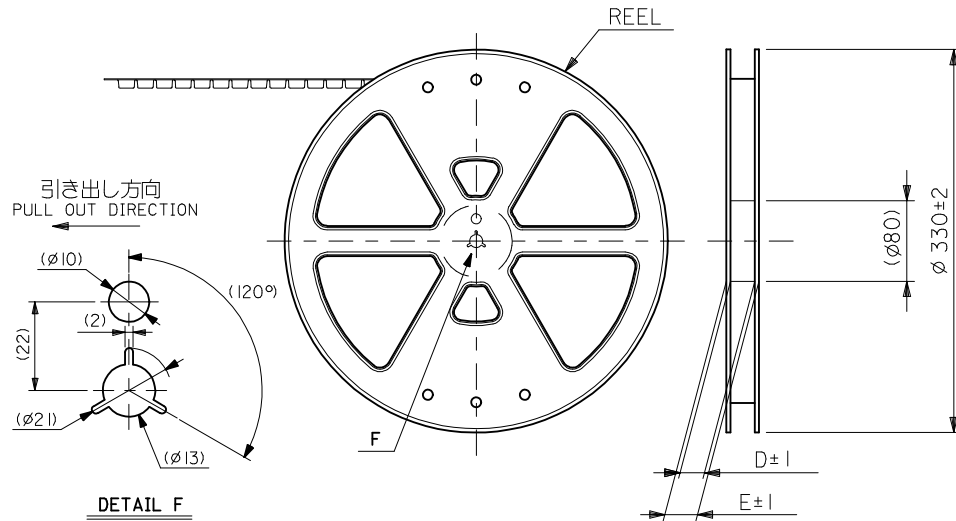
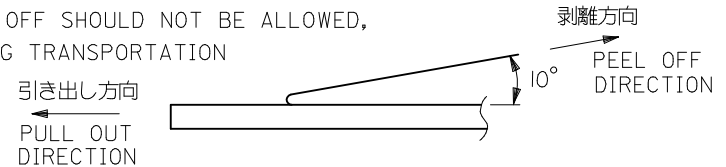
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

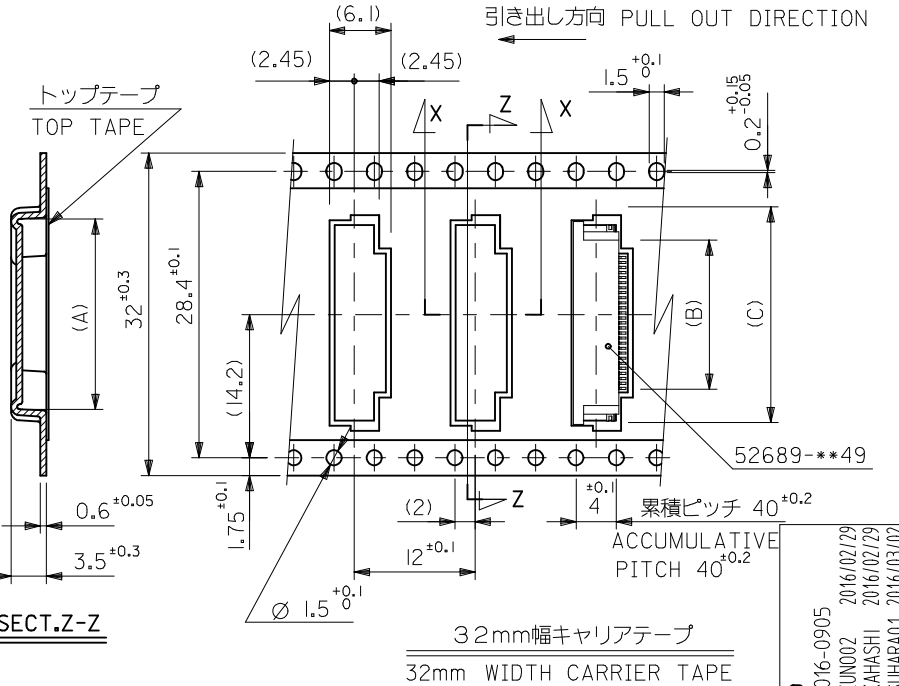
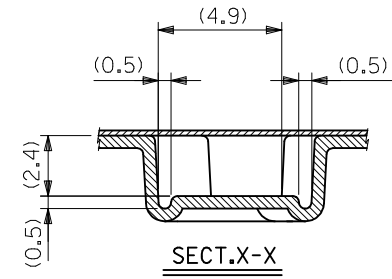
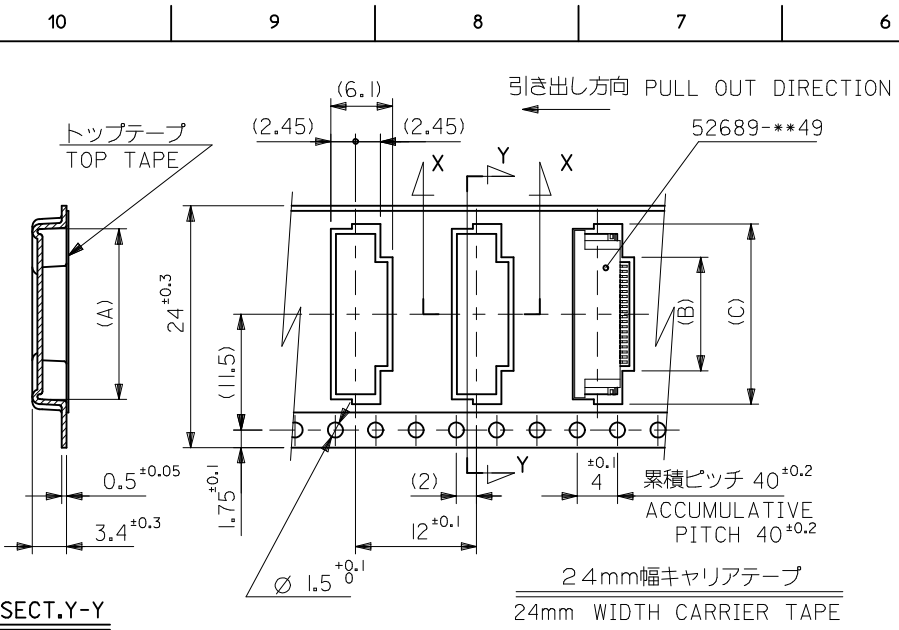
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォーム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED	EC NO: J2016-0905	2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	DRWN: YIMIZUNO02	2016/02/29	0.25 UNDER	UNDER	±0.03	MM ONLY		---	METRIC	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE- molex DOCUMENT NO. SD-52689-035 SHEET NO. 1 OF 3
	CHKD: TAKAHASHI	2016/02/29	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TILE		
	APPR: KUSUHARA01	2016/03/02	0.5 OVER	1.0 UNDER	±0.1	H. KAWABATA	2004/02/03	CHECKED BY	DATE	
			1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03	APPROVED BY	DATE	
		10 OVER	30 UNDER	±0.25	M. SASAO	2004/02/03	MATERIAL NO.			
		30 OVER		±0.3	SEE SHEET 2,3					
			ANGULAR	±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



24	29.4	25.4	32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
						21.4	14.8	20.4	-2887	28
						17.4	10.8	16.4	-2087	20
						16.4	9.8	15.4	-1887	18
						15.4	8.8	14.4	-1687	16
						14.9	8.3	13.9	-1587	15
						13.4	6.8	12.4	-1287	12
						12.4	5.8	11.4	-1087	10
						11.4	4.8	10.4	-0887	8
						10.9	4.3	9.9	-0787	7
			10.4	3.8	9.4	-0687	6			
			9.9	3.3	8.9	52689 -0587	5			

REVISED	EC NO: J2016-0905	2016/02/29	2016/02/29	2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	DRWN: YIMZUN02	CHKD: TAKAHASHI	APPR: KUSUHARA01	0.25 UNDER						UNDER	±0.03
				0.25 OVER						0.5 UNDER	±0.05
				0.5 OVER						1.0 UNDER	±0.1
				1.0 OVER						10 UNDER	±0.2
			10 OVER	30 UNDER	±0.25						
			30 OVER		±0.3						
			ANGULAR	±							

MODEL NO.	52689-**-87	CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	52689 -0587	種別	CIRCUIT
DRAWN BY H.KAWABATA DATE 2004/02/03											
CHECKED BY K.TOJO DATE 2004/02/03											
APPROVED BY M.SASAO DATE 2004/02/03											
TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-											
DOCUMENT NO. SD-52689-035											
SHEET NO. 2 OF 3											

F

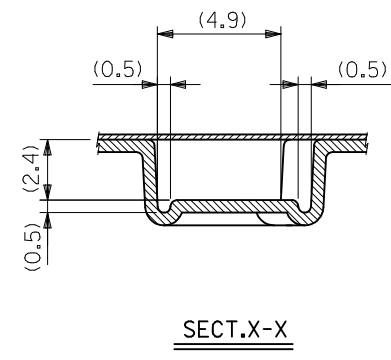
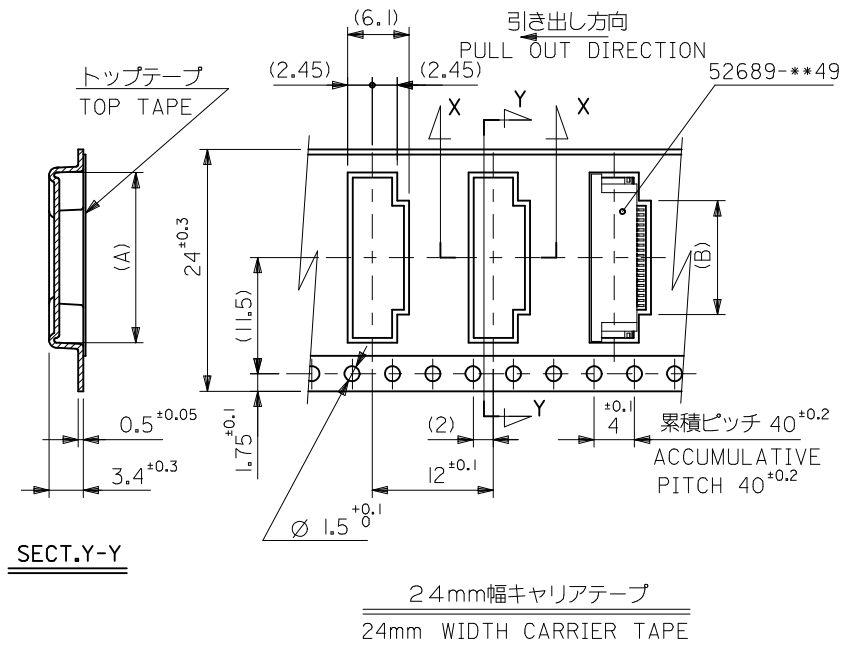
E

D

C

B

A



24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO. 極数 CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/29 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
30 OVER		±0.3	M. SASAO	2004/02/03	SEE TABLE	SD-52689-035	3 OF 3	
ANGULAR	±3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								